

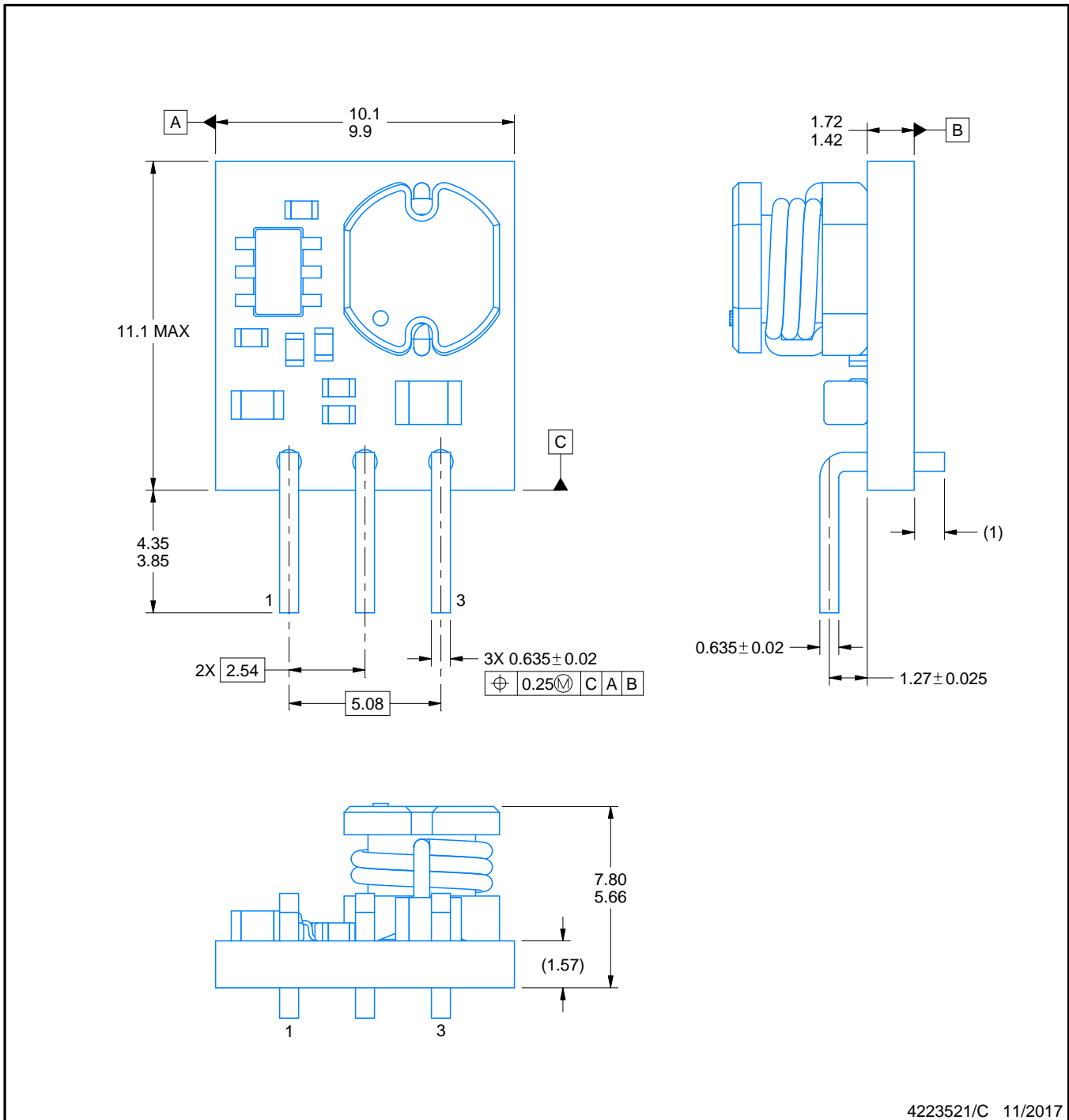
EAB0003A



# PACKAGE OUTLINE

SIPMODULE - 11.1 mm max height

SYSTEM IN PACKAGE MODULE



NOTES:

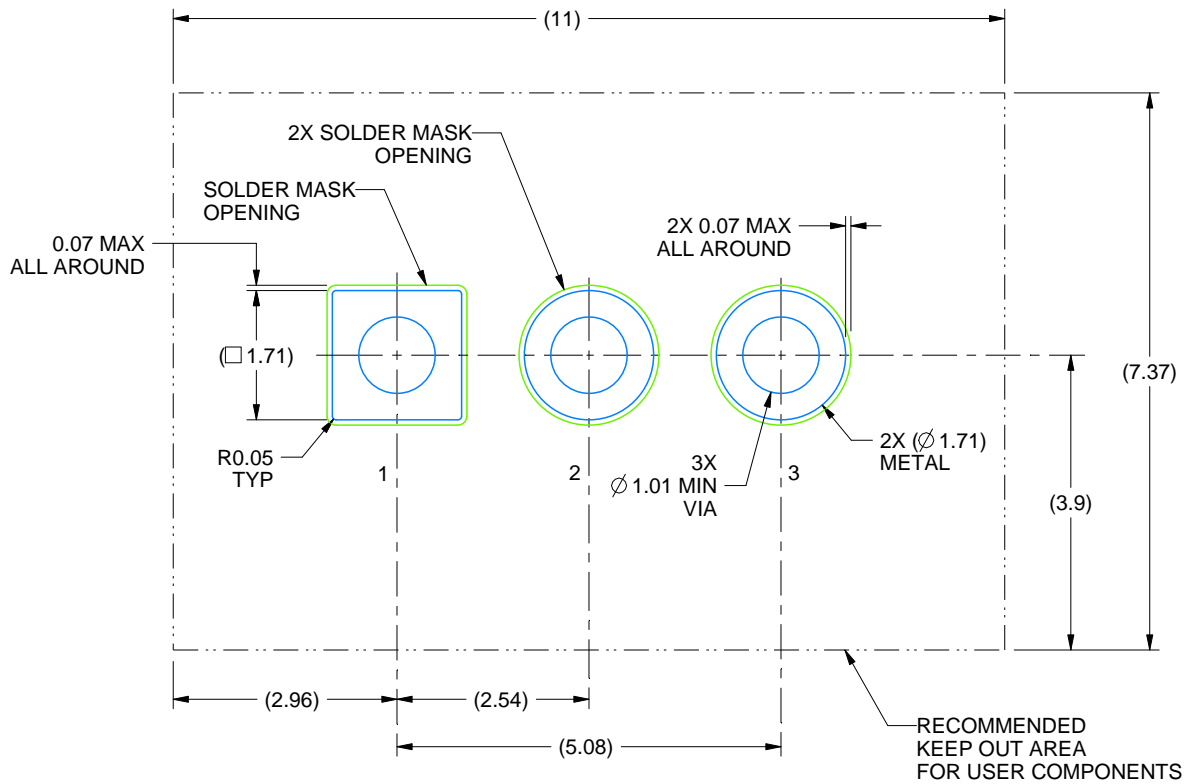
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Location, size and quantity of each component are for reference only and may vary.

# EXAMPLE BOARD LAYOUT

EAB0003A

SIPMODULE - 11.1 mm max height

SYSTEM IN PACKAGE MODULE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE:10X

4223521/C 11/2017

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